CLAIMS

1. A device, comprising: a first substrate comprising first and second surfaces; a plurality of conductive contacts on the first surface of the first substrate; a dielectric on the first surface of the first substrate and having a plurality of openings; and a plurality of conductive posts coupled to at least some of the plurality of conductive contacts, wherein the dielectric at least partially surrounds the plurality of conductive posts, wherein the plurality of conductive contacts are in contact with and protrude beyond the first surface of the first substrate, and wherein at least one of the plurality of conductive contacts extends through the first substrate so as to be in contact with and protrude beyond the second surface of the first substrate.

2. The device of claim 1, wherein the first substrate comprises a first interposer.

3. The device of claim 1, wherein the dielectric comprises a photoimageable dielectric (PID).

4. The device of claim 1, wherein the plurality of conductive posts comprise a plurality of copper posts.

5. The device of claim 1, further comprising a plurality of conductive pads coupled to the plurality of conductive posts, respectively.

6. The device of claim 5, wherein the plurality of conductive pads comprise a plurality of copper pads.

7. The device of claim 1, wherein the plurality of conductive contacts are a first plurality of conductive contacts, and wherein the device further comprises: a second substrate comprising first and second surfaces; and a second plurality of conductive contacts on the first surface of the second substrate.

8. The device of claim 7, wherein the second substrate comprises a second interposer.

9. The device of claim 7, wherein the plurality of conductive posts are electrically coupled to at least some of the second plurality of conductive contacts.

10. The device of claim 9, further comprising a plurality of solder balls coupled between the plurality of conductive posts and the at least some of the second plurality of conductive contacts, respectively.

11. The device of claim 7, further comprising an integrated circuit die within an opening in the dielectric.

12. The device of claim 11, wherein the integrated circuit die is disposed on the first surface of the second substrate.

13. The device of claim 12, wherein the integrated circuit die is a first the integrated circuit die, and wherein the device further comprises a second integrated circuit die disposed on the second surface of the second substrate.

14. The device of claim 13, further comprising a mold on the second surface of the first substrate and the second integrated circuit die.

15. An integrated circuit package, comprising: a first substrate having first and second surfaces; a first plurality of conductive contacts on the first surface of the first substrate; a second substrate having first and second surfaces; a second plurality of conductive contacts on the first surface of the second substrate; a dielectric disposed between the first surface of the first substrate and the first surface of the second substrate, the dielectric having a plurality of openings; a plurality of conductive posts disposed within some but not all of the openings in the dielectric, the plurality of conductive posts electrically coupled to at least some of the first plurality of conductive contacts on the first surface of the first substrate and at least some of the second plurality of conductive contacts on the first surface of the second substrate; and an integrated circuit die disposed on the first surface of the second substrate within one of the openings of the dielectric not occupied by one of the plurality of conductive posts, wherein the plurality of conductive contacts are in contact with and protrude beyond the first surface of the first substrate, and wherein at least one of the plurality of conductive contacts extends through the first substrate so as to be in contact with and protrude beyond the second surface of the first substrate.

16. The integrated circuit package of claim 15, wherein the first substrate comprises a first interposer, and wherein the second substrate comprises a second interposer.

17. The integrated circuit package of claim 15, wherein the dielectric comprises a photoimageable dielectric (PID).

18. The integrated circuit package of claim 15, wherein the plurality of conductive posts comprise a plurality of copper posts.

19. The integrated circuit package of claim 15, further comprising a plurality of conductive pads coupled to the plurality of conductive posts, respectively.

20. The integrated circuit package of claim 19, wherein the plurality of conductive pads comprise a plurality of copper pads.

21. The integrated circuit package of claim 15, further comprising a plurality of solder balls coupled between the plurality of conductive posts and the at least some of the second plurality of conductive contacts on the first surface of the second substrate, respectively.

22. The integrated circuit package of claim 15, wherein the integrated circuit die is a first the integrated circuit die, and wherein the integrated circuit package further comprises a second integrated circuit die disposed on the second surface of the first substrate.

23. The integrated circuit package of claim 22, further comprising a mold on the second surface of the first substrate and the second integrated circuit die.

24. The device of claim 5, wherein a combined height of the plurality of conductive posts and the plurality of conductive pads extend beyond a height of the dielectric.

25. The integrated circuit package of claim 19, wherein a combined height of the plurality of conductive posts and the plurality of conductive pads extend beyond a height of the dielectric.

26. The integrated circuit package of claim 15, further comprising a plurality of solder balls coupled between the plurality of conductive posts and the at least some of the first plurality of conductive contacts on the first surface of the first substrate, respectively.